

<b>PCN Number:</b>	20161216000			<b>PCN Date:</b>	Dec 10, 2016									
<b>Title:</b>	Qualify New Assembly Material set for Selected Device(s)													
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services											
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Mar 10, 2017	<b>Estimated Sample Availability:</b>	Date provided at sample request											
<b>Change Type:</b>														
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site									
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material									
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials									
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process									
<b>PCN Details</b>														
<b>Description of Change:</b>														
Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:														
<table border="1"> <thead> <tr> <th>Material</th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>4042504</td> <td><a href="#">4211470</a></td> </tr> <tr> <td>Mold compound</td> <td>4205255</td> <td><a href="#">4222198</a></td> </tr> </tbody> </table>						Material	Current	Proposed	Mount compound	4042504	<a href="#">4211470</a>	Mold compound	4205255	<a href="#">4222198</a>
Material	Current	Proposed												
Mount compound	4042504	<a href="#">4211470</a>												
Mold compound	4205255	<a href="#">4222198</a>												
<b>Reason for Change:</b>														
Continuity of supply														
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>														
None														
<b>Anticipated impact on Material Declaration</b>														
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>											
<b>Changes to product identification resulting from this PCN:</b>														
None														
<b>Product Affected:</b>														
ADS8555SPM	ADS8556IPM	ADS8557IPM	ADS8558IPM											
ADS8555SPMR	ADS8556IPMR	ADS8557IPMR	ADS8558IPMR											



## Qualification Report

### Mount compound and mold compound change on ADS855xSPM and ADS855xIPM family

Approve Date 16-Dec-2016

#### Product Attributes

Attributes	Qual Device: ADS8555SPM	QBS Product Reference: ADS8556IPM/R	QBS Process Reference: DAC8871IPW
Assembly Site	TAI	TAI	CRS
Package Family	LQFP	LQFP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL94 Class V-0
Wafer Fab Supplier	DMOS5	DMOS5	DMOS5
Wafer Process	50HPA07HV	50HPA07HV	50HPA07HV

- QBS: Qual By Similarity

- Qual Device ADS8555SPM is qualified at LEVEL3-260C

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS8555SPM	QBS Product Reference: ADS8556IPM	QBS Process Reference: DAC8871IPW
AC	Autoclave 121C	96 Hours	-	-	3/231/0
CDM	ESD - CDM	500 V	3/9/0	1/3/0	3/9/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	3/230/0	-	3/231/0
HBM	ESD - HBM	2000 V	-	1/3/0	3/9/0
HTOL	Life Test, 150C	500 Hours	-	-	3/348/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	-	3/231/0
LU	Latch-up	(per JESD78)	-	1/6/0	3/18/0
PD	Physical Dimensions	(per mechanical drawing)	1/5/0	-	-
TC	Temperature Cycle -65C/150C	500 Cycles	3/231/0	-	3/231/0
TS	Thermal Shock - 65/150C	500 Cycles	-	-	3/231/0

Type	Test Name / Condition	Duration	Qual Device: ADS8555SPM	QBS Product Reference: ADS8556IPM	QBS Process Reference: DAC8871IPW
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>